

Amendments to the Specification

Please replace the first full paragraph on page 14 with the following:

An adhesion layer 200 and an electroplating seed layer 202 are now formed, also as previously described with reference to Fig. 12a, and as shown in Fig. ~~13~~14. Copper or gold 210 is electroplated up from seed layer 202 to fill openings 7' and 7, as well as above polymer layer 5, as depicted in Fig. 15. Chemical mechanical planarization (CMP) is used to remove the plated metal ~~210~~210, seed layer 202, and adhesion layer 200, above polymer 5, stopping on ~~seed layer 202~~polymer layer 5. This forms via plugs 212 above and connecting to contact points 6, as shown in Fig. 16. Via plugs 212 have a width of between about 1 and 300 um.